

**LISTING OF CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A semiconductor device comprising:

a semiconductor member having thereon a plurality of electrode terminals; and  
a mounting member having a plurality of interconnect pads electrically and mechanically connected to the respective electrode terminals for mounting the semiconductor member on the mounting member,

the interconnect pads forming a plurality of I/O cells including signal terminals, a portion of the I/O cells forming a first group of I/O cells and another portion of the I/O cells forming a second group of I/O cells disposed on an inner position of the mounting member with respect to the first group of I/O cells, the first group of I/O cells including a plurality of rows of interconnect pads disposed to encircle a center of the mounting member, and the second group of I/O cells including a plurality of rows of interconnect pads disposed to encircle a center of the mounting member, the first and second groups of I/O cells being disposed directly under the semiconductor member, wherein:

the first group of I/O cells are arranged in a first row, a first column perpendicular to the first row,~~[[and]]~~ a second row disposed on an inner position relative to the first row, and a second column that is perpendicular to the second row and disposed on an inner position relative to the first column,

the second group of I/O cells are arranged in a thirdfirst row, a third column  
perpendicular to the third row, [[and]] a fourthsecond row disposed on an inner position relative  
to the thirdfirst row, and a fourth column that is perpendicular to the fourth row and disposed on  
an inner position relative to the third column,

each of the first and second rows and first and second columns of the first group of I/O  
cells is arranged parallel to any portion of an outer periphery of the semiconductor member, and  
each of the thirdfirst and fourthsecond rows of the second group of I/O cells is arranged  
parallel to any portion of the outer periphery of the semiconductor member.

2. (Original) The semiconductor device as defined in claim 1, wherein the semiconductor  
member is a semiconductor chip, the electrode terminals are internal electrodes disposed on a  
bottom surface of the semiconductor chip, and the mounting member is a package substrate  
used for packaging thereon the semiconductor chip.

3. (Previously Presented) The semiconductor device as defined in claim 1, wherein the  
mounting member is a semiconductor package for mounting the semiconductor member on a  
mounting substrate, the semiconductor package includes ball electrodes disposed on a bottom  
surface of a packaging substrate, and the mounting substrate forms a specified circuit by  
mounting the semiconductor package thereon.

4. (Previously Presented) The semiconductor device as defined in claim 1, wherein the I/O cells  
include only the signals terminals or terminals for signals, power and ground intermingled  
among one another.

5. (Previously Presented) The semiconductor device as defined in claim 4, wherein the I/O cells include peripherals.

6. (Previously Presented) The semiconductor device as defined in claim 1, wherein an interconnect line is electrically connected to each of the interconnect pads, and the interconnect lines electrically connected to the interconnect pads of at least one of the I/O cells are formed in a single interconnect layer.

7. (Previously Presented) The semiconductor device as defined in claim 6, wherein the interconnect pads and the interconnect lines electrically connected to the interconnect pads in the single interconnect layer are formed on the surface of a packaging substrate.

8. (Previously Presented) The semiconductor device as defined in claim 7, wherein the interconnect lines connected to the I/O cells located on inner positions extend between the I/O cells located on an outer periphery.

9. (Original) The semiconductor device as defined in claim 6, wherein the interconnect pads and the interconnect lines electrically connected to the interconnect pads are formed as a multi-layered interconnect layer in the substrate.

10. (Original) The semiconductor device as defined in claim 9, wherein at least one of the first group and the second group includes an outer group and an inner group disposed on the inner position of the mounting member with respect to the outer group.

11. (Previously Presented) The semiconductor device as defined in claim 10, wherein the interconnect lines electrically connected to the interconnect pads corresponding to the first group of I/O cells and the interconnect lines electrically connected to the interconnect pads corresponding to the second group of I/O cells are formed in different interconnect layers.